

MDD03 SERIES OF TECS - THE MOST POPULAR TEC SERIES FOR MINIATURE TELECOMMUNICATION SYSTEMS

MDD03 Series of RMT TECs became the most popular TEC Series for cooling and temperature stabilization of miniature telecommunication systems with high heat power density.

MDD03 Series was developed to meet the requirement of increasing the optimal operating temperature range of TECs. Such requirement was caused by the increased chip heat load on TEC. This Series of TECs is the evolution of earlier developed MD03 Series with up to 50% additional maximum cooling capacity within the same TEC size. MDD03 Series TECs based on RMT SuperHD pellet placement technology with 600 elements per cm² pellet density. Such TECs provide up to 28 W/cm² cooling power density



Fig.1 – Pellet density comparison of 1MD03-008-XX TEC and 1MDD03-012-XX TEC of the same size

Due to its design features, MDD03 Series TECs have the highest cooling capacity among microTECs comparing to the MD02 and MD03 Series. This advantage makes MDD03 Series TECs the most suitable for miniature LD-applications using the small headers (TO46, TO56, BOX TOSA and smaller) with strong dimensional and power consumption limits.

Moreover, all options as well as Au-Sn inner solder, Wire Bonding Posts, **Posts-free design** and others can be applied to MDD03 Series TECs at the Customer's request.

Please contact RMT concerning MDD03 Series of TECs and for selection of the most optimal TEC solutions for your applications.

Web-link:

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